

L3510 Remanufacturing Specifications:

Test & Qualification

- Configured to customer specification
- Demonstrated at ESI prior to ship
- Full Process 1000 wafers using plasma without error
- No wafer radiation damage during test

Gasonics L3510 Process and Control Enhancements

- Software version 7.50
- New Pentium® SBC CPU Card
- LCD display and new keypad"
- Single cassette processing
- True Downstream Microwave plasma processing
- Automatic photoemission end-point detection
- Calibrated Microwave system
- Calibrated Pressure system
- Calibrated Temperature Control system

e3510 Advanced Process Control System

- Upgrade your Gasonics L3510 to our advanced ESI e3511 in one day
- Plug and Play, plugs directly into the L3510 wiring harness
- IDX Flexware software
- Embedded PC and I/O System
- 17" touchscreen

L3510 Electrical Improvements



- New Wiring harness
- New Heated platen, Platen overtemp protection system available as an upgrade
- Wafer cooling station with touch wafer sensor, works with glass, GaS etc.
- Lamp assembly with new reflector and bulb with solid state controller
- New UV igniter bulb and power supply
- Advanced DC Power supplies and A/C distribution with all SSR's
- New Gerling GL139 1.2kw microwave generator, Mititoyo 3 stub tuner, waveguide and 6 pole mw applicator
- Latest model I/O PCB and Pressure/EOP PCBs
- MKS ISO valve, new ATM sensor and new MKS baratron

Mechanical Improvements

- System Hardware compatible for 75-200mm wafers
- Advanced Hine Hatm-5 pick and place robot
- Pneumatics Adjusting block for door and lifter, puts all speed adjustments in one place where they are easy to get at.
- UV igniter power supply relocated to top of gas box for easy access
- KalRez® high temp O-rings for better resistance to plasma and UV

Plumbing and Pneumatics

- New MKS throttle valve
- Three gas inputs with customer specified MFC's (typically 4L O2, 2L N2 and 500cc O2)
- New Gas box, Solenoid valves, air cylinders, Tubing